NOTES:

1. ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5-1982.
2. DATUM PLANE -H- LOCATED AT MOLD PARTING LINE AND COINCIDENT WITH LEAD, WHERE LEAD EXITS PLASTIC BODY AT BOTTOM OF PARTING LINE.
3. DATUMS A-B AND -D- TO BE DETERMINED AT CENTERLINE BETWEEN LEADS WHERE LEADS EXIT PLASTIC BODY AT DATUM PLANE -H- .
4. TO BE DETERMINED AT SEATING PLANE -C- .
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
6. 'N' IS THE TOTAL NUMBER OF TERMINALS.
7. THESE DIMENSIONS TO BE DETERMINED AT DATUM PLANE -H- .
8. THE TOP OF PACKAGE IS SMALLER THAN THE BOTTOM OF PACKAGE BY 0.15 MILLIMETERS.
9. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.
10. CONTROLLING DIMENSION: MILLIMETER.
11. MAXIMUM ALLOWABLE DIE THICKNESS TO BE ASSEMBLED IN THIS PACKAGE FAMILY IS 0.30 MILLIMETERS.
12. THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MS-026, VARIATIONS ACB, ACC, ACD & ACE.
13. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.
14. DIMENSION D2 AND E2 REPRESENT THE SIZE OF THE EXPOSED PAD. THE ACTUAL DIMENSIONS ARE SPECIFIED ON THE BONDING DIAGRAM, AND IS DEPENDENT ON THE DIE SIZE.
15. EXPOSED PAD SHALL BE COPLANAR WITH BOTTOM OF PACKAGE WITHIN 0.05.
16. CORNER CHAMFER OF EXPOSED DIE PAD SHALL BE WITHIN 1.0 mm.

SYMBOL	JEDEC VARIATION ACB ALL DIMENSIONS IN MILLIMETERS			NOTE
	MIN.	NOR.	MAX.	
A	---	---	1.20	
A_1	0.05	---	0.15	13
A_2	0.95	1.00	1.05	
D	12.00 BSC.			4
D_1	10.00 BSC.			7,8
E	12.00 BSC.			4
E_1	10.00 BSC.			7,8
L	0.45	0.60	0.75	
N	44			
e	0.80 BSC.			
b	0.30	0.37	0.45	9
b1	0.30	0.35	0.40	
ccc	---	---	0.10	
ddd	---	---	0.20	

SYMBOL	JEDEC VARIATION ACC ALL DIMENSIONS IN MILLIMETERS			NOTE
	MIN.	NOR.	MAX.	
A	---	---	1.20	
A_1	0.05	---	0.15	13
A_2	0.95	1.00	1.05	
D	12.00 BSC.			4
D_1	10.00 BSC.			7,8
E	12.00 BSC.			4
E_1	10.00 BSC.			7,8
L	0.45	0.60	0.75	
N	52			
e	0.65 BSC			
b	0.22	0.32	0.38	9
b1	0.22	0.30	0.33	
ccc	---	---	0.10	
ddd	---	---	0.13	

SYMBOL	JEDEC VARIATION ACD ALL DIMENSIONS IN MILLIMETERS			NOTE
	MIN.	NOR.	MAX.	
A	---	---	1.20	
A_1	0.05	---	0.15	13
A_2	0.95	1.00	1.05	
D	12.00 BSC.			4
D_1	10.00 BSC.			7,8
E	12.00 BSC.			4
E_1	10.00 BSC.			7,8
L	0.45	0.60	0.75	
N	64			
e	0.50 BSC.			
b	0.17	0.22	0.27	9
b1	0.17	0.20	0.23	
ccc	---	---	0.08	
ddd	---	---	0.08	

SYMBOL	JEDEC VARIATION ACE ALL DIMENSIONS IN MILLIMETERS			NOTE
	MIN.	NOR.	MAX.	
A	---	---	1.20	
A_1	0.05	---	0.15	13
A_2	0.95	1.00	1.05	
D	12.00 BSC.			4
D_1	10.00 BSC.			7,8
E	12.00 BSC.			4
E_1	10.00 BSC.			7,8
L	0.45	0.60	0.75	
N	80			
e	0.40 BSC.			
b	0.13	0.18	0.23	9
b1	0.13	0.16	0.19	
ccc	---	---	0.08	
ddd	---	---	0.07	

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Amkor Technology Philippines, Inc.
Manila, Philippines

Amkor Technology / ANAM Semiconductor

TITLE: PACKAGE OUTLINE, TQFP, 10X10 mm BODY, 1.00/0.10 mm FORM, 1.00 mm THICK, (OPTIONAL ePAD)

SIZE: A3 | DWG NUMBER: 32772 | REV: 10

SCALE: 6:1 | PRINTING IS SCALED TO FIT DO NOT SCALE DRAWING | SHEET: 2 OF 2

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